



PATENT  
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Tongbi JIANG

Serial No.: 09/484,437

Filed: January 18, 2000

Title: DIE ATTACH CURE METHOD FOR  
SEMICONDUCTOR DEVICE

) Art Unit: 2822

) Examiner: J. Mitchell

RECEIVED  
NOV 13 2001  
1C 2822 MAIL ROOM

#5  
D.Scott  
11-1601

REQUEST FOR DRAWINGS CHANGE

JMM  
11/29/01  
Approved

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Applicant proposes to substitute the enclosed drawing (FIG. 1) for the originally-filed Figure 1. The Examiner's approval is solicited.

The enclosed drawing includes a change which is consistent with the original drawings. Furthermore, the enclosed drawing contains no new matter. The proposed drawings change is provided to insure complete compliance to 37 C.F.R. §§ 1.83 and 1.84.

Allowance of the drawings change is solicited.

Respectfully submitted,

By: \_\_\_\_\_

Thomas J. D'Amico

Registration No.: 28,371

DICKSTEIN SHAPIRO MORIN &

OSHINSKY LLP

2101 L Street NW

Washington, DC 20037-1526

(202) 785-9700

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